



Applied Materials Achieves Milestone 1,000th HDP-CVD System Shipment

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SANTA CLARA, Calif.--(BUSINESS WIRE)--July 19, 2005--Applied Materials, Inc. has shipped its 1,000th HDP-CVD (high-density plasma chemical vapor deposition) system--the industry standard for depositing critical gap-fill dielectric films for five chip generations. The advanced Applied Centura(R) Ultima HDP-CVD(R) is already system of record at both 65nm logic and 70nm memory customers for applications as diverse as shallow trench isolation (STI), pre-metal dielectric (PMD), inter-metal dielectric (IMD) and passivation fill.

According to Gartner Dataquest, Applied Materials has maintained the leading position in HDP-CVD technology since the launch of its first system in 1996 and has also increased its market share in the HDP-CVD segment by 9% in calendar year 2004. Applied Materials continues to break through the barriers of each technology node with its Ultima HDP-CVD by optimizing chamber design and process. The Ultima system is currently used by 7 of the top 10 semiconductor manufacturers worldwide.

"Applied's Ultima system is the industry's workhorse tool for all HDP-CVD applications and is one of the most extendible gap-fill products our customers have ever used," said Dr. Farhad Moghadam, senior vice president and general manager of Applied Materials' Thin Films Product Business Group. "The system provides unparalleled high aspect ratio gap-fill technology and productivity required for fabricating 65nm-generation transistors, as well as the high-performance interconnects in many types of memory chips that are powering today's consumer devices. Customers are already planning new applications for our HDP-CVD technology for next generation devices."

The overwhelming success of the Applied Ultima HDP-CVD system is the result of several proprietary breakthroughs that have enabled customers to achieve the productivity, extendibility and cost-efficiency needed for five-generations of manufacturing. The Ultima is the first HDP-CVD system to feature dual RF coils for superior gap-fill capability; its innovative Blue(TM) monopolar electrostatic chuck enables excellent film and dopant uniformity; and its pioneering Remote Plasma Clean(TM) provides exceptional defect and mean-wafer-between clean performance with reduced cost of consumables. Advanced doped and undoped applications can be processed using the same chamber, enabling customers to substantially lower capital investment and improve production effectiveness.

Applied Materials, Inc. (Nasdaq:AMAT), headquartered in Santa Clara, California, is the largest supplier of equipment and services to the global semiconductor industry. Applied Materials' web site is www.appliedmaterials.com

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